

INFORMATION DISCLOSURE
CITATION IN AN
APPLICATION
(PTO-1449)



ATTY. DOCKET NO.
005920 USA/
PMG/PCTRL

SERIAL NO.
09/943,383

APPLICANT
SHANMUGASUNDRAM et al.

FILING DATE
August 31, 2001

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2823

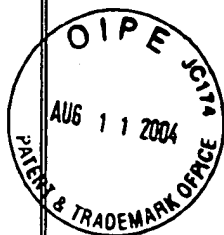
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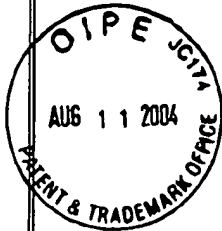
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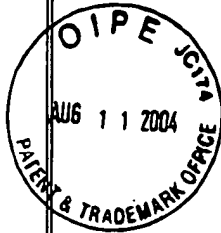
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















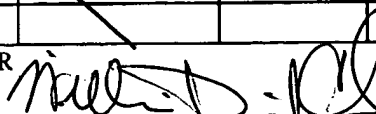
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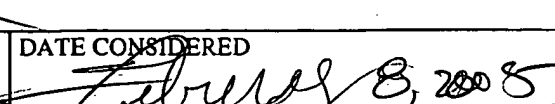
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